

**IGBT Modules** 

### **Power Module (X series)** 1700V / 600A / 2-in-1 package

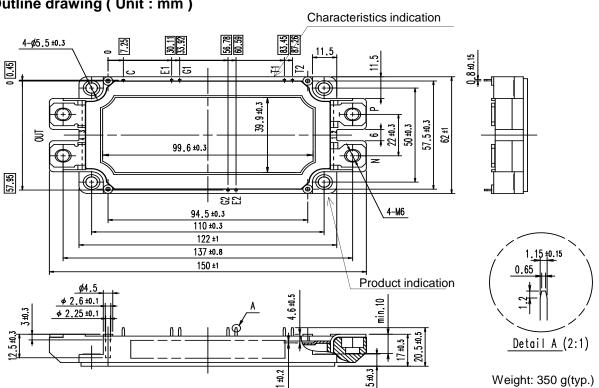
#### **■** Features

Low V<sub>CE(sat)</sub> Low Inductance Module structure Solder pin terminals

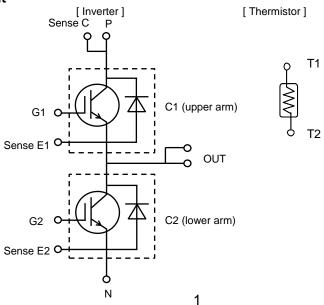
#### ■ Applications

Inverter for Motor Drives, AC and DC Servo Drives Uninterruptible Power Supply Systems, Wind Turbines, PV Power Conditioning Systems





#### **■** Equivalent Circuit



NOTE) shows theoretical dimension and tolerance is  $\Phi \emptyset 0.5$ 



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### ■ Absolute Maximum Ratings (at T<sub>C</sub>= 25°C unless otherwise specified)

		Items	Symbols	Cond	itions	Maximum Ratings	Units	
	Collecto	r-emitter voltage, gate-emitter short-circuited	V <sub>CES</sub>			1700	V	
	Gate-em	nitter voltage, collector-emitter short-circuited	$V_{GES}$			±20	V	
	Collecto	r current	I <sub>C</sub>	Continuous	T <sub>C</sub> =100°C	600		
	Repetitiv	ve peak collector current	I <sub>CRM</sub>	1ms	•	1200		
rter	Forward	current	I <sub>F</sub>			600	A	
l ve	Repetitive peak forward current		I <sub>FRM</sub>	1ms		1200		
-	Total power dissipation		P <sub>tot</sub>	1 device		3845	W	
	Virtual junction temperature		$T_{\rm vj}$			175		
	Operating virtual junction temperature		т	T			175	]
	(under s	witching conditions)	$T_{\rm vjop}$			175	°C	
Ca	se tempe	rature	T <sub>c</sub>			125		
Storage temperature		$T_{\rm stg}$			-40 ~ 125			
Isolation between terminal and copper base (*1)		$V_{isol}$	AC: 1min.		3400	Vrms		
voltage between thermistor and others (*2)		v isol	AC. IIIIII.		3400	VIIIIS		
Мо	Mounting torque of screws to heatsink (*3)		Ms	M5		6.0	N⋅m	
Мо	Mounting torque of screws to terminals (*3)		$M_{\rm t}$	M6		6.0		

<sup>(\*1)</sup> All terminals should be connected together during the test.

(\*3) Recommendable Value: : Mounting torque of screws to heatsink Recommendable Value: : Mounting torque of screws to terminals  $2.5 \sim 6.0 \text{ N} \cdot \text{m}$  (M5)  $3.5 \sim 6.0 \text{ N} \cdot \text{m}$  (M6)

<sup>(\*2)</sup> Two thermistor terminals should be connected together, other terminals should be connected together and shorted to base plate during the test.

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### ■ Electrical characteristics (at $T_{vj}$ = 25°C unless otherwise specified)

	Itama	Cumbala	bols Conditions			Characteristics			
	Items	Symbols	Conditio	min.	typ.	max.	Units		
	Collector-emitter cut-off current, gate-emitter short-circuited	I <sub>CES</sub>	$V_{GE} = 0V$ $V_{CE} = 1700V$		-	-	150	μA	
	Gate leakage current, collector-emitter short-circuited	I <sub>GES</sub>		V <sub>CE</sub> =0V, V <sub>GE</sub> =±20V		-	300	nA	
	Gate-emitter threshold voltage	V <sub>GE(th)</sub>	$V_{\text{CE}} = 20V$ $I_{\text{C}} = 600 \text{mA}$			6.5	7.0	V	
		V <sub>CE(sat)</sub> (terminal)		T <sub>vj</sub> =25°C	-	2.50	2.95		
	Collector-emitter		$V_{\rm GE} = 15 \rm V$	T <sub>vj</sub> =25°C	-	1.70	2.15	V	
	saturation voltage	V <sub>CE(sat)</sub>	I <sub>C</sub> = 600A	T <sub>vj</sub> =125°C	-	2.10	-	7	
		(chip)		T <sub>vj</sub> =150°C	-	2.25	-		
				T <sub>vi</sub> =175°C	-	2.35	-		
	Internal gate resistance	$r_{\rm g}$	-	,	-	1.67	-	Ω	
		C <sub>ies</sub>			-	75	-		
	Capacitance	Coes	V <sub>CE</sub> =10V, V <sub>GE</sub> =0V, f=1MHz		-	2.1	-	nF	
		C <sub>res</sub>	1		-	0.47	-	1	
	Gate charge $V_{\rm CC} = 900 \text{V}, I$		$V_{\rm CC} = 900 \text{V}, I_{\rm C}$ $V_{\rm GE} = -15 \rightarrow +18$		-	4.7	-	μC	
ier	Forward voltage	V <sub>F</sub> (terminal)	$V_{GE} = 0V$ $I_{F} = 600A$	T <sub>vj</sub> =25°C	-	2.50	2.95		
nverter				T <sub>vj</sub> =25°C	-	1.70	2.15	V	
=	Forward voltage	V <sub>F</sub>		T <sub>vj</sub> =125°C	-	1.80	-		
		(chip)		T <sub>vi</sub> =150°C	-	1.85	-		
				T <sub>vi</sub> =175°C	-	1.80	-		
		t <sub>d(on)</sub>	$V_{\rm CC} = 900 V$	T <sub>vi</sub> =25°C	-	0.49	-		
			$I_{\rm C}$ , $I_{\rm F} = 600$ A	T <sub>vj</sub> =125°C	-	0.60	-		
			$V_{GE} = +15/-15 \text{ V}$	T <sub>vj</sub> =150°C	-	0.61	-		
			$R_G = \pm 1\Omega$	T <sub>vj</sub> =175°C	-	0.62	-		
			$L_{\rm S} = 35  \rm nH$	T <sub>vj</sub> =25°C	-	0.11	-		
	Switching time (*1)			T <sub>vj</sub> =125°C	-	0.12	-		
		t <sub>r</sub>		$T_{\rm vj}$ =150°C	-	0.13	-		
				<i>T</i> <sub>vj</sub> =175°C	-	0.14	-		
				$T_{\rm vj}$ =25°C	-	0.58	-		
		$t_{\rm d(off)}$		$T_{\rm vj}$ =125°C	-	0.63	-	μs	
		a d(OII)		$T_{vj} = 150^{\circ} \text{C}$	-	0.65	-	_	
			1	$T_{vj} = 175^{\circ}C$	-	0.66	-		
				$T_{vj}$ =25°C $T_{vj}$ =125°C	-	0.42	-	-	
		$t_{f}$		$T_{vj}$ =125 C $T_{vj}$ =150°C	-	0.61 0.66	-	-	
				$T_{vi} = 175^{\circ}C$		0.71	-		
			1	$T_{\rm vi}$ =25°C	-	0.30	-	1	
	Reverse recovery time	<b>+</b>		T <sub>vi</sub> =125°C	-	0.41	-		
	Treverse recovery unite	t <sub>rr</sub>		$T_{\rm vi}$ =150°C	-	0.46	-		
				T <sub>vj</sub> =175°C	-	0.55	-		

<sup>(\*1)</sup> Turn on time  $(t_{on}) = t_{d(on)} + t_{r}$ , Turn off time  $(t_{off}) = t_{d(off)} + t_{f}$ 



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### ■ Electrical characteristics (at $T_{vj}$ = 25°C unless otherwise specified)

Items		Symbols	Symbols		Conditions		Characteristics			
	items	Symbols				min.	typ.	max.	Units	
		E <sub>on</sub>	V <sub>CC</sub> =	900V	$T_{\rm vj}$ =25°C	-	152	-	-	
					T <sub>vj</sub> =125°C	-	194	-		
			$V_{\rm GE} =$	+15/-15 V	T <sub>vj</sub> =150°C	-	212	-		
				±1Ω	<i>T</i> <sub>vj</sub> =175°C	-	241	-		
		E <sub>off</sub>	$L_{S} =$	35 nH	$T_{\rm vj}$ =25°C	-	140	-		
ē	(per pulse)				T <sub>vj</sub> =125°C	-	177	-		
nverter					T <sub>vj</sub> =150°C	-	188	-	mJ	
드					T <sub>vj</sub> =175°C	-	198	-		
					T <sub>vj</sub> =25°C	-	70	-		
					T <sub>vj</sub> =125°C	-	128	-		
					T <sub>vj</sub> =150°C	-	143	-		
						T <sub>vj</sub> =175°C	-	165	-	
tor	Resistance	R	T =	25°C		-	5000	-	Ω	
nis	TOSISIATIOO	11	T =	100°C		465	495	520		
Thermistor	B value	В	T =	25/ 50°C		3305	3375	3450	К	

#### NOTICE:

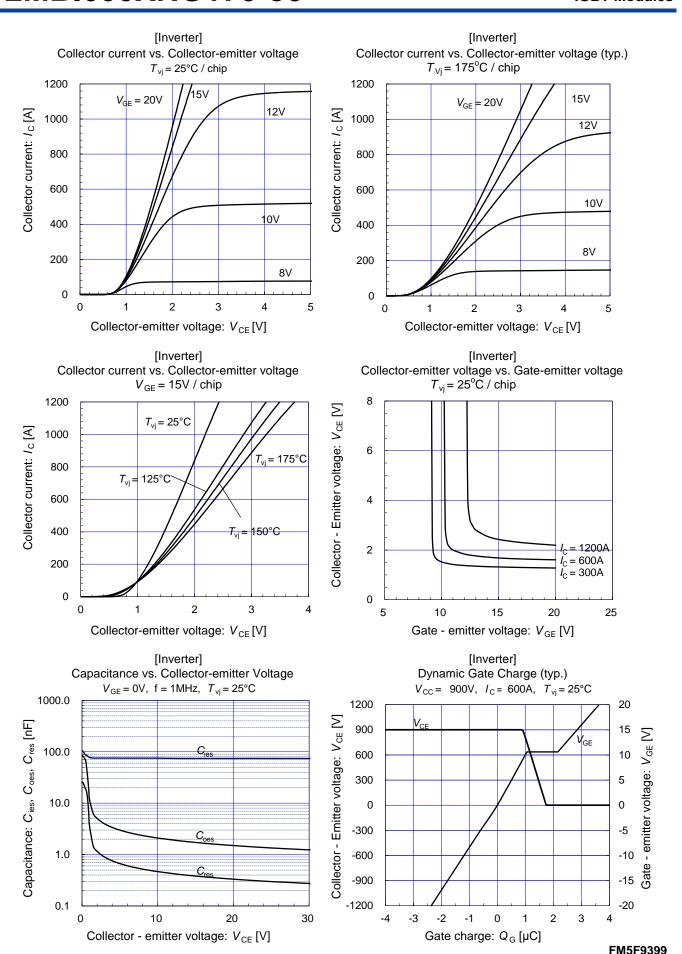
The external gate resistance ( $R_{\rm G}$ ) shown above is one of our recommended value for the purpose of minimum switching loss. However the optimum  $R_{\rm G}$  depends on circuit configuration and/or environment. We recommend that the  $R_{\rm G}$  has to be carefully chosen based on consideration if IGBT module matches design criteria, for example, switching loss, EMC/EMI, spike voltage, surge current and no unexpected oscillation and so on.

#### ■Thermal resistance characteristics

Items	Symbols	Conditions	Ch	Units		
items	Syllibols	Conditions	min.	typ.	max.	Units
Thermal resistance junction to	D	Inverter IGBT	-	-	0.039	
case(1 device)	$R_{ ext{th(j-c)}}$	Inverter FWD	-	-	0.055	K/W
Thermal resistance case to heatsink(1 IGBT+1 FWD) (*1)	$R_{ ext{th(c-s)}}$	with 1 W/(m·K) thermal grease	-	0.0167	-	10,44

<sup>(\*1)</sup> This is the value which is defined mounting on the additional heatsink with thermal grease.

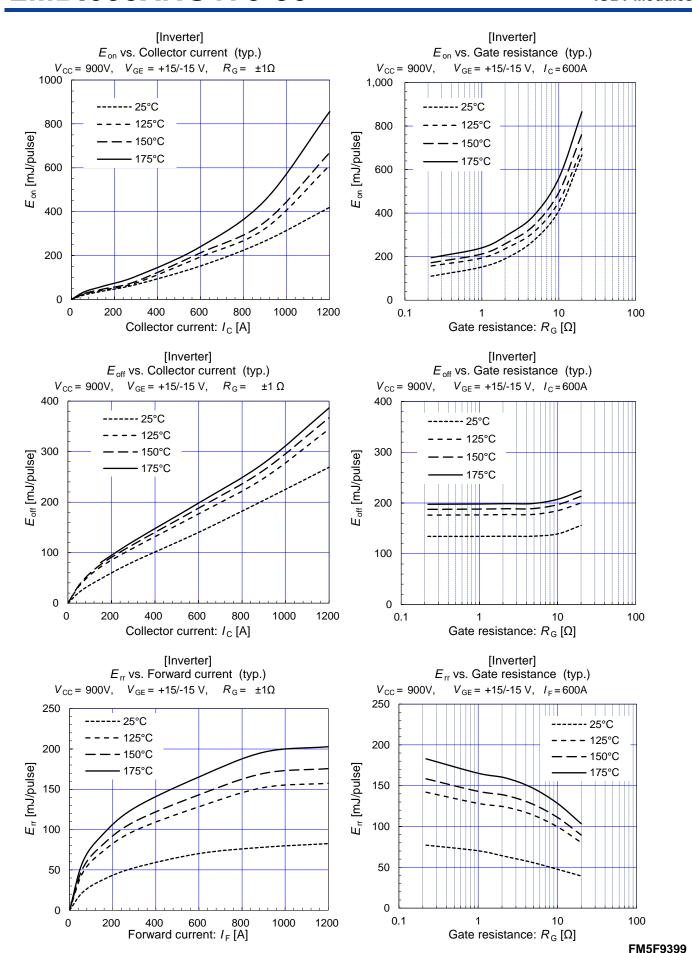




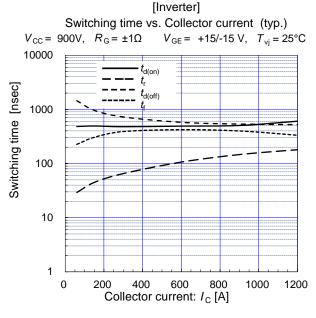


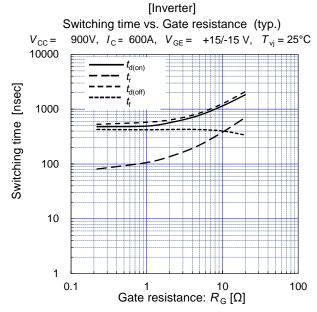
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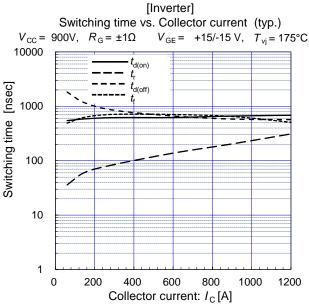
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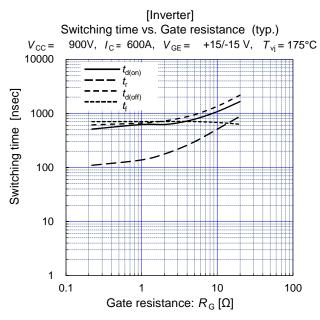


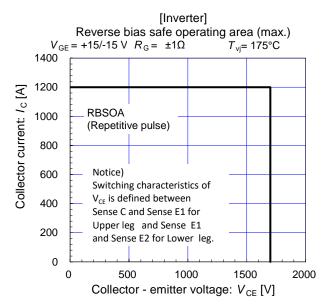


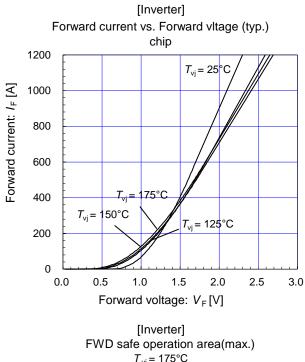


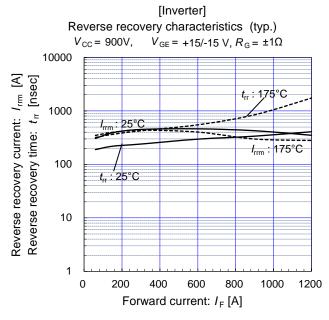


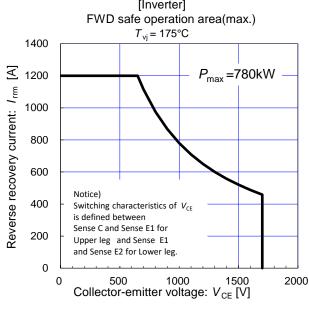


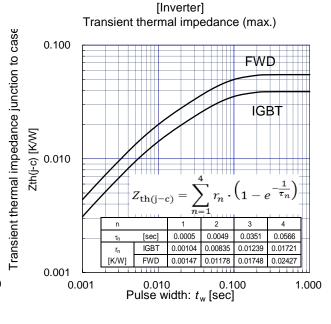


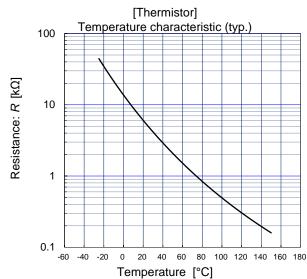












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